



## Advance Product Change Notification

201712013A

**Issue Date:** 15-Dec-2017

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### Management Summary

Assembly transfer of the FXOS8700CQR1 from Amkor Korea (ATK1) to ASE-ChungLi Taiwan (ASECL) assembly site for continuous customer supply.

### Change Category

|  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input checked="" type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

**FXOS8700CQR1 ASECL Transfer and Copper Wire Qualification**

### Details of this Planned Change

NXP Semiconductors announces the assembly transfer of FXOS8700CQR1 to ASE-ChungLi Taiwan (ASECL) assembly site. These products were previously assembled at the Amkor Korea (ATK1) assembly site.

With this change, NXP Semiconductors also announces the materials change to Gold Palladium Copper (AuPdCu) wire, Sumitomo EME-G700LA version P mold compound, Ablestik Die Attach Film (DAF) ATB-125, and Shinko Rough Copper Tin Plated (CuSn) C7025 material for FXOS8700CQR1. These products were previously assembled with Gold (Au) wire, Sumitomo EME-G700 mold compound, Henkel ATB-125 Die Attach Film and LGI (STW) Roughened PPF (micro NiPdAuAg) C7025 material. Qualification data will be available after qualification completion in April 2018.

### Why do we Plan this Change

The transfer to ASECL is for supply continuity as a result of ATK1 closure. The transfer from Gold to Gold

Palladium Copper wire is an alignment to industry standard convention for wirebond material type. The change to mold compound and die attach material for QFN 3x3 package is required to standardize the bill of materials for ASECL assembly production.

#### **Identification of Affected Products**

Product identification does not change

There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 2nd digit of the tracecode.

### **Product Availability**

#### **Sample Information**

Samples are available from 26-Jan-2018

#### **Production**

Planned first shipment 28-May-2018

### **Impact**

no impact to the product's functionality anticipated.

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Timing and Logistics**

The Self Qualification Report will be ready on 27-Apr-2018.

The Final PCN is planned to be issued on: 27-Apr-2018.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Jan-2018.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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**Position** Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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| Changed Orderable Part# | Changed Part 12NC | Changed Part Number | Changed Part Description | Package Name | Status | Product Line |
|-------------------------|-------------------|---------------------|--------------------------|--------------|--------|--------------|
| FXOS8700CQR1            | 935311011547      | FXOS8700CQR1        | 3-Axis Mag 3-Axis Accel  | TQFN16       | RFS    | BL Sensors   |